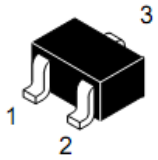
WNM6002

Single N-Channel, 60V, 0.30A, Power MOSFET

Http//:www.sh-willsemi.com

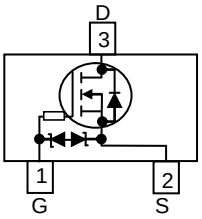
V_{DS} (V)	Rds(on) (Ω)
60	1.4@ V_{GS}=10V
	1.7@ V_{GS}=4.5V
ESD Rating:2000V HBM	



SOT-323

Descriptions

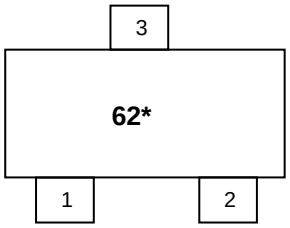
The WNM6002 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS\ (ON)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM6002 is Pb-free and Halogen-free.



Pin configuration (Top view)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-323



62 = Device Code

* = Month (A~Z)

Marking

Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

Order information

Device	Package	Shipping
WNM6002-3/TR	SOT-323	3000/Reel&Tape

Absolute Maximum ratings

Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	60		V
Gate-Source Voltage		V_{GS}	±20		
Continuous Drain Current [ad]	T_A=25°C	I_D	0.30	0.28	A
	T_A=70°C		0.24	0.22	
Maximum Power Dissipation [ad]	T_A=25°C	P_D	0.37	0.31	W
	T_A=70°C		0.23	0.20	
Continuous Drain Current [bd]	T_A=25°C	I_D	0.27	0.24	A
	T_A=70°C		0.21	0.19	
Maximum Power Dissipation [bd]	T_A=25°C	P_D	0.29	0.23	W
	T_A=70°C		0.18	0.14	
Pulsed Drain Current [c]		I_{DM}	1.0		A
Operating Junction Temperature		T_J	-55 to 150		°C
Lead Temperature		T_L	260		°C
Storage Temperature Range		T_{stg}	-55 to 150		°C

Thermal resistance ratings

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance [a]	t ≤ 10 s	$R_{\theta JA}$	245	335	°C/W
	Steady State		325	395	
Junction-to-Ambient Thermal Resistance [b]	t ≤ 10 s	$R_{\theta JA}$	375	430	
	Steady State		445	535	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	260	300	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

b Surface mounted on FR-4 board using minimum pad size, 1oz copper

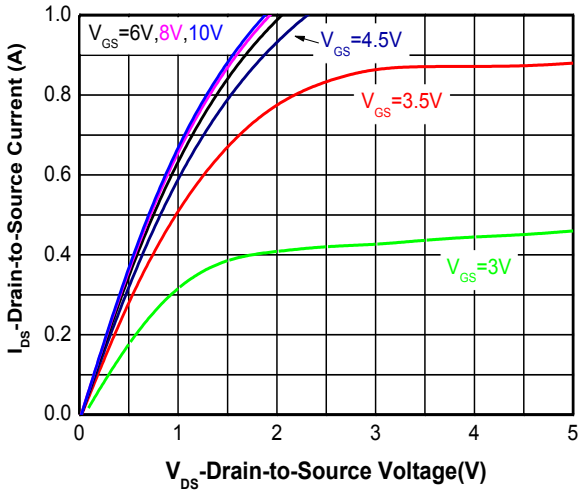
c Pulse width<380μs

d Maximum junction temperature T_J=150°C.

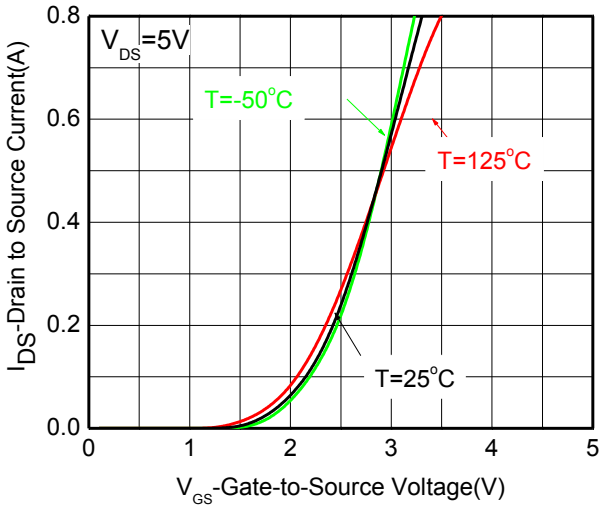
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	V_{GS} = 0 V, I_D = 250uA	60			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} =60V, V_{GS} = 0V			1	uA
Gate-to-source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} =±20V			±5	uA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250uA	0.8	1.3	2	V
Drain-to-source On-resistance [b, c]	$R_{DS(on)}$	V_{GS} = 10V, I_D = 0.37A		1.4	2.0	Ω
		V_{GS} = 4.5V, I_D = 0.2A		1.7	2.6	
Forward Transconductance	g_{FS}	V_{DS} =15V, I_D =0.25A		0.42		S
CAPACITANCES, CHARGES						
Input Capacitance	C_{ISS}	V_{GS} = 0 V,		23.37		pF
Output Capacitance	C_{OSS}	f = 1.0 MHz,		7.33		
Reverse Transfer Capacitance	C_{RSS}	V_{DS} = 25V		5.2		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 10 V, V_{DD} = 30 V, I_D =0.37A		1.2		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.15		
Gate-to-Source Charge	Q_{GS}			0.21		
Gate-to-Drain Charge	Q_{GD}			0.12		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V_{DD}=30V, I_D=0.2A, V_{GEN}=10V,R_G=10 Ω		7.6		ns
Rise Time	tr			5.1		
Turn-Off Delay Time	td(OFF)			24.6		
Fall Time	tf			10		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	V_{GS} = 0 V, I_S =0.3A		0.9	1.5	V

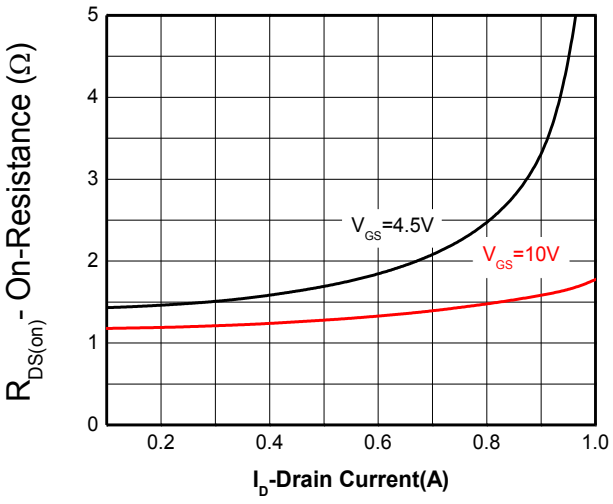
Typical Characteristics (Ta=25°C, unless otherwise noted)



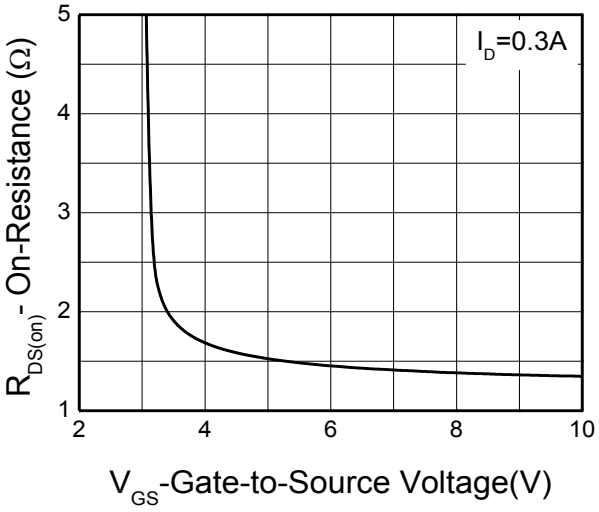
Output characteristics



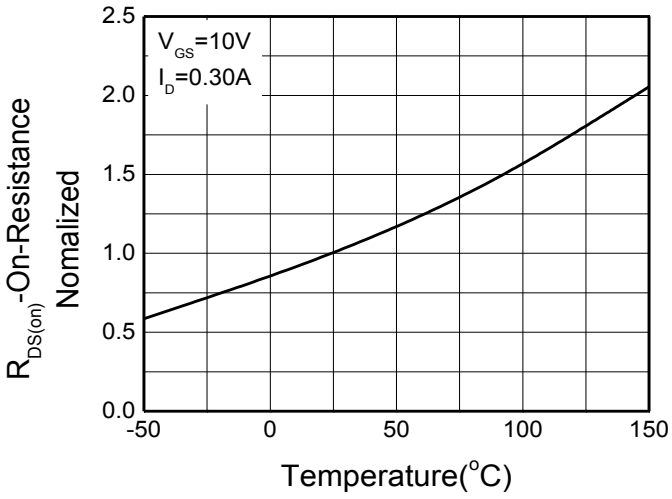
Transfer characteristics



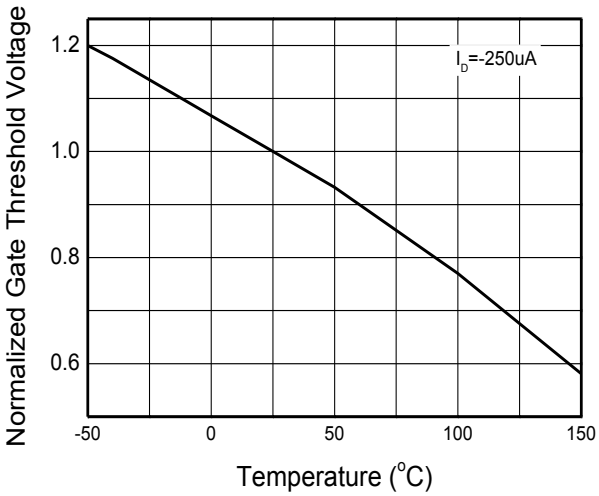
On-Resistance vs. Drain current



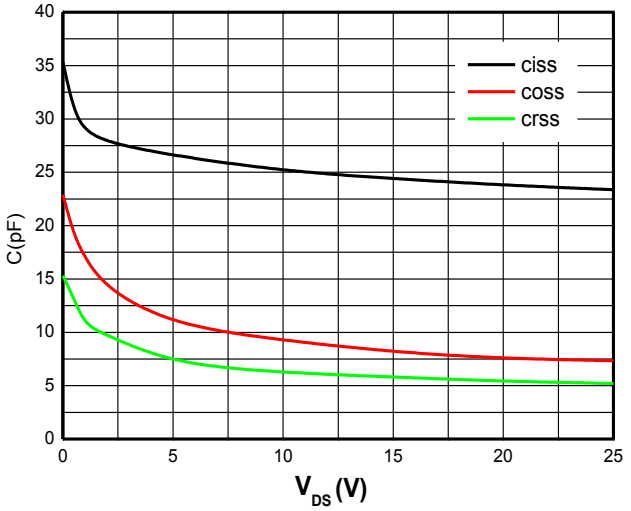
On-Resistance vs. Gate-to-Source voltage



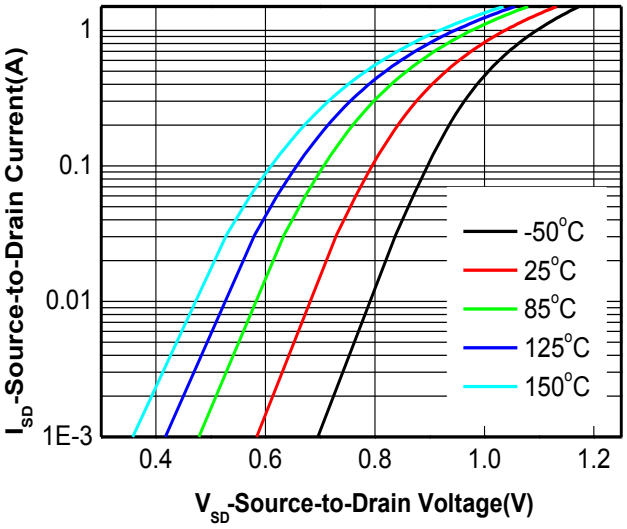
On-Resistance vs. Junction temperature



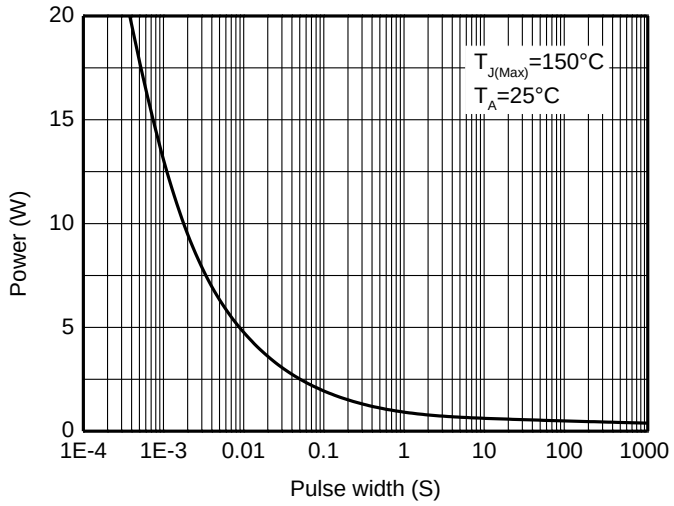
Threshold voltage vs. Temperature



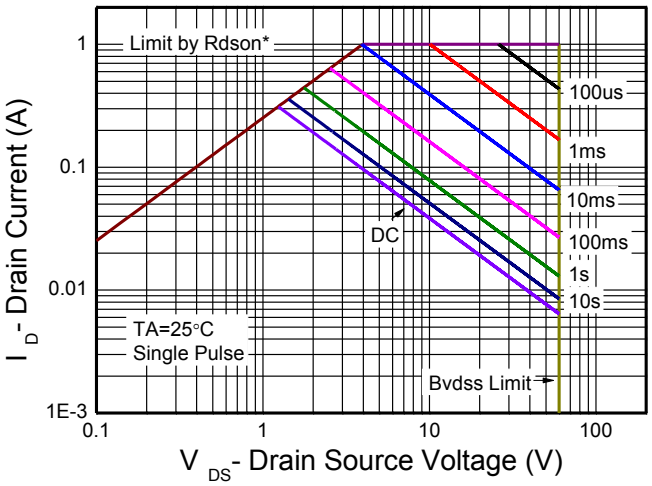
Capacitance



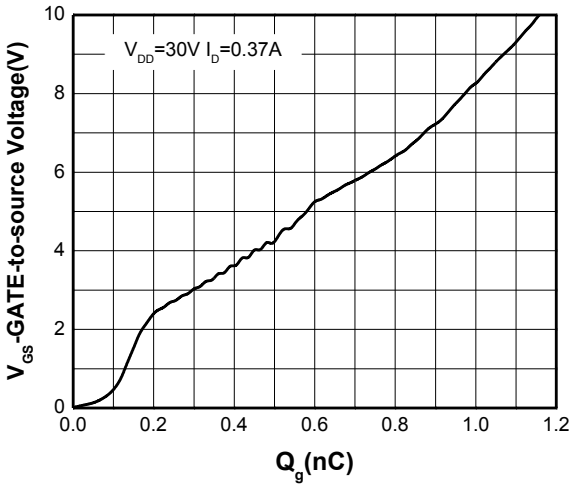
Body diode forward voltage



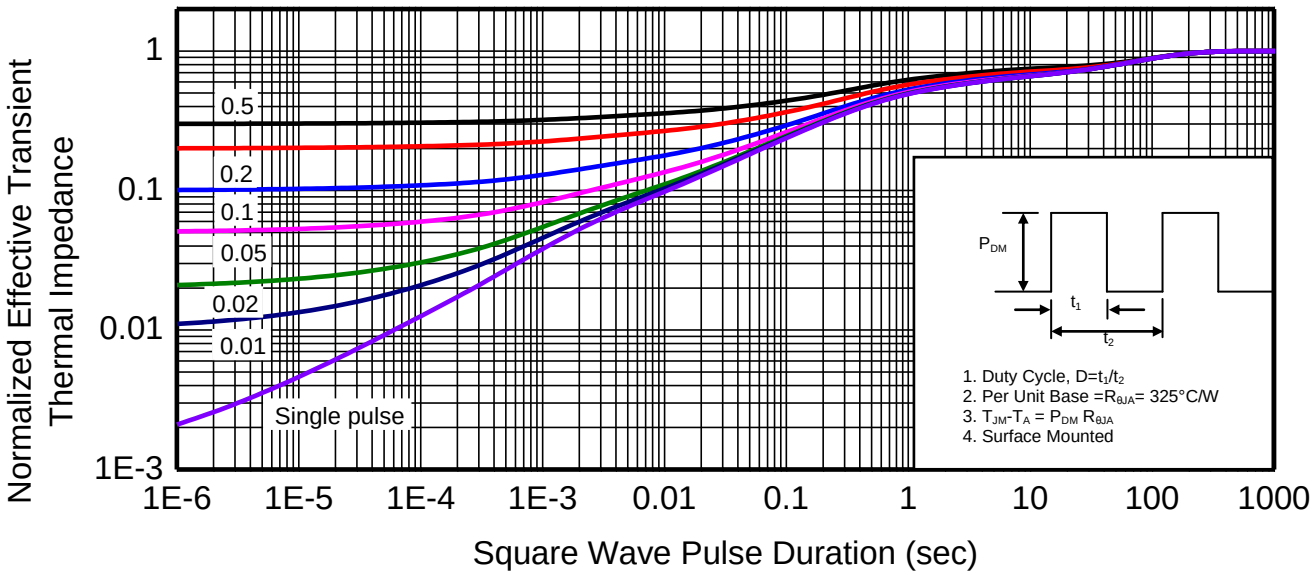
Single pulse power



Safe operating power



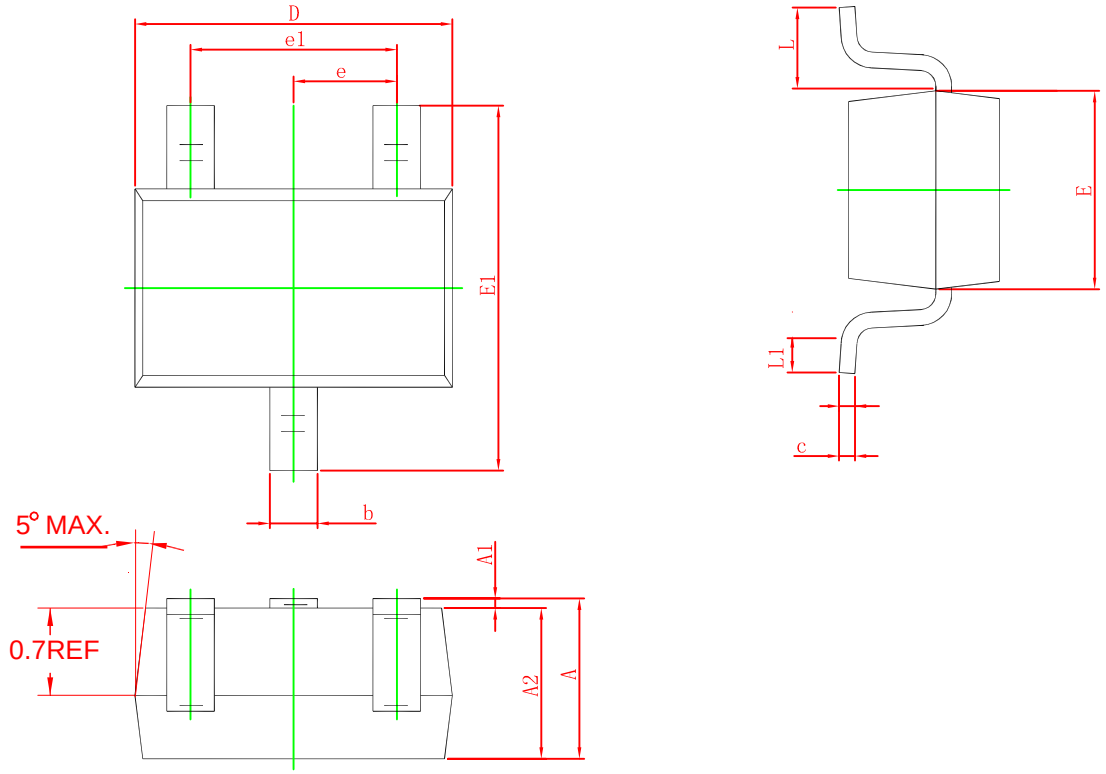
Gate Charge Characteristics



Transient thermal response (Junction-to-Ambient)

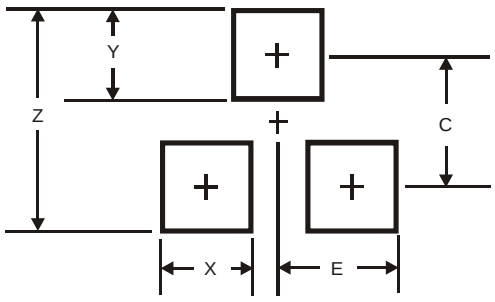
Package outline dimensions

SOT-323



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A1		0.1MAX.	
A2	0.800	0.900	1.000
b	0.250	0.300	0.350
c	0.050	0.100	0.150
D	1.900	2.000	2.100
E	1.150	1.250	1.350
E1	2.000	2.100	2.200
e1	1.200	1.300	1.400
L1		0.2MIN.	

Recommend PCB Layout (Unit: mm)



Dimensions	SOT323
Z	2.8
X	0.7
Y	0.9
C	1.9
E	1.0

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.